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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	18
Program Memory Size	8KB (2.75K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 9x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f08ka101-i-ss

TABLE 1-1: DEVICE FEATURES FOR THE PIC24F16KA102 FAMILY

Features	PIC24F08KA101	PIC24F16KA101	PIC24F08KA102	PIC24F16KA102
Operating Frequency	DC – 32 MHz			
Program Memory (bytes)	8K	16K	8K	16K
Program Memory (instructions)	2816	5632	2816	5632
Data Memory (bytes)	1536			
Data EEPROM Memory (bytes)	512			
Interrupt Sources (soft vectors/NMI traps)	30 (26/4)			
I/O Ports	PORTA<6:0> PORTB<15:12, 9:7, 4, 2:0>		PORTA<7:0> PORTB<15:0>	
Total I/O Pins	18		24	
Timers: Total Number (16-bit) 32-Bit (from paired 16-bit timers)	3 1			
Input Capture Channels	1			
Output Compare/PWM Channels	1			
Input Change Notification Interrupt	17		23	
Serial Communications: UART SPI (3-wire/4-wire) I^2C™	2 1 1			
10-Bit Analog-to-Digital Module (input channels)	9			
Analog Comparators	2			
Resets (and delays)	POR, BOR, RESET Instruction, $\overline{MCLR}$, WDT, Illegal Opcode, REPEAT Instruction, Hardware Traps, Configuration Word Mismatch (PWRT, OST, PLL Lock)			
Instruction Set	76 Base Instructions, Multiple Addressing Mode Variations			
Packages	20-Pin PDIP/SSOP/SOIC/QFN		28-Pin SPDIP/SSOP/SOIC/QFN	

TABLE 1-2: PIC24F16KA102 FAMILY PINOUT DESCRIPTIONS

Function	Pin Number				I/O	Input Buffer	Description
	20-Pin PDIP/SSOP/ SOIC	20-Pin QFN	28-Pin SPDIP/ SSOP/SOIC	28-Pin QFN			
AN0	2	19	2	27	I	ANA	A/D Analog Inputs
AN1	3	20	3	28	I	ANA	
AN2	4	1	4	1	I	ANA	
AN3	5	2	5	2	I	ANA	
AN4	7	4	6	3	I	ANA	
AN5	8	5	7	4	I	ANA	
AN10	17	14	25	22	I	ANA	
AN11	16	13	24	21	I	ANA	
AN12	15	12	23	20	I	ANA	
U1BCLK	13	10	18	15	O	—	UART1 IrDA® Baud Clock
U2BCLK	9	6	11	8	O	—	UART2 IrDA Baud Clock
C1INA	8	5	7	4	I	ANA	Comparator 1 Input A (Positive Input)
C1INB	7	4	6	3	I	ANA	Comparator 1 Input B (Negative Input Option 1)
C1INC	5	2	5	2	I	ANA	Comparator Input C (Negative Input Option 2)
C1IND	4	1	4	1	I	ANA	Comparator Input D (Negative Input Option 3)
C1OUT	17	14	25	22	O	—	Comparator 1 Output
C2INA	5	2	5	2	I	ANA	Comparator 2 Input A (Positive Input)
C2INB	4	1	4	1	I	ANA	Comparator 2 Input B (Negative Input Option 1)
C2INC	8	5	7	4	I	ANA	Comparator 2 Input C (Negative Input Option 2)
C2IND	7	4	6	3	I	ANA	Comparator 2 Input D (Negative Input Option 3)
C2OUT	14	11	20	17	O	—	Comparator 2 Output
CLKI	7	4	9	6	I	ANA	Main Clock Input Connection
CLKO	8	5	10	7	O	—	System Clock Output

Legend: ST = Schmitt Trigger input buffer, ANA = Analog level input/output, I^2C™ = I^2C/SMBus input buffer

Note 1: Alternative multiplexing when the I2C1SEL Configuration bit is cleared.

TABLE 1-2: PIC24F16KA102 FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Function	Pin Number				I/O	Input Buffer	Description
	20-Pin PDIP/SSOP/ SOIC	20-Pin QFN	28-Pin SPDIP/ SSOP/SOIC	28-Pin QFN			
CN0	10	7	12	9	I	ST	Interrupt-on-Change Inputs
CN1	9	6	11	8	I	ST	
CN2	2	19	2	27	I	ST	
CN3	3	20	3	28	I	ST	
CN4	4	1	4	1	I	ST	
CN5	5	2	5	2	I	ST	
CN6	6	3	6	3	I	ST	
CN7	—	—	7	4	I	ST	
CN8	14	11	20	17	I	ST	
CN9	—	—	19	16	I	ST	
CN11	18	15	26	23	I	ST	
CN12	17	14	25	22	I	ST	
CN13	16	13	24	21	I	ST	
CN14	15	12	23	20	I	ST	
CN15	—	—	22	19	I	ST	
CN16	—	—	21	18	I	ST	
CN21	13	10	18	15	I	ST	
CN22	12	9	17	14	I	ST	
CN23	11	8	16	13	I	ST	
CN24	—	—	15	12	I	ST	
CN27	—	—	14	11	I	ST	
CN29	8	5	10	7	I	ST	
CN30	7	4	9	6	I	ST	
CVREF	17	14	25	22	O	ANA	Comparator Voltage Reference Output
CTED1	14	11	20	17	I	ST	CTMU Trigger Edge Input 1
CTED2	15	12	23	20	I	ST	CTMU Trigger Edge Input 2
CTPLS	16	13	24	21	O	—	CTMU Pulse Output
IC1	14	11	19	16	I	ST	Input Capture 1 Input
INT0	11	8	16	13	I	ST	External Interrupt Inputs
INT1	17	14	25	22	I	ST	
INT2	14	11	20	17	I	ST	
HLVDIN	15	12	23	20	I	ANA	HLVD Voltage Input
$\overline{MCLR}$	1	18	1	26	I	ST	Master Clear (device Reset) Input
OC1	14	11	20	17	O	—	Output Compare/PWM Outputs
OCFA	17	14	25	22	I	—	Output Compare Fault A
OSCI	7	4	9	6	I	ANA	Main Oscillator Input Connection
OSCO	8	5	10	7	O	ANA	Main Oscillator Output Connection

Legend: ST = Schmitt Trigger input buffer, ANA = Analog level input/output, I^2C™ = I^2C/SMBus input buffer

Note 1: Alternative multiplexing when the I2C1SEL Configuration bit is cleared.

4.0 MEMORY ORGANIZATION

As with Harvard architecture devices, the PIC24F microcontrollers feature separate program and data memory space and busing. This architecture also allows the direct access of program memory from the data space during code execution.

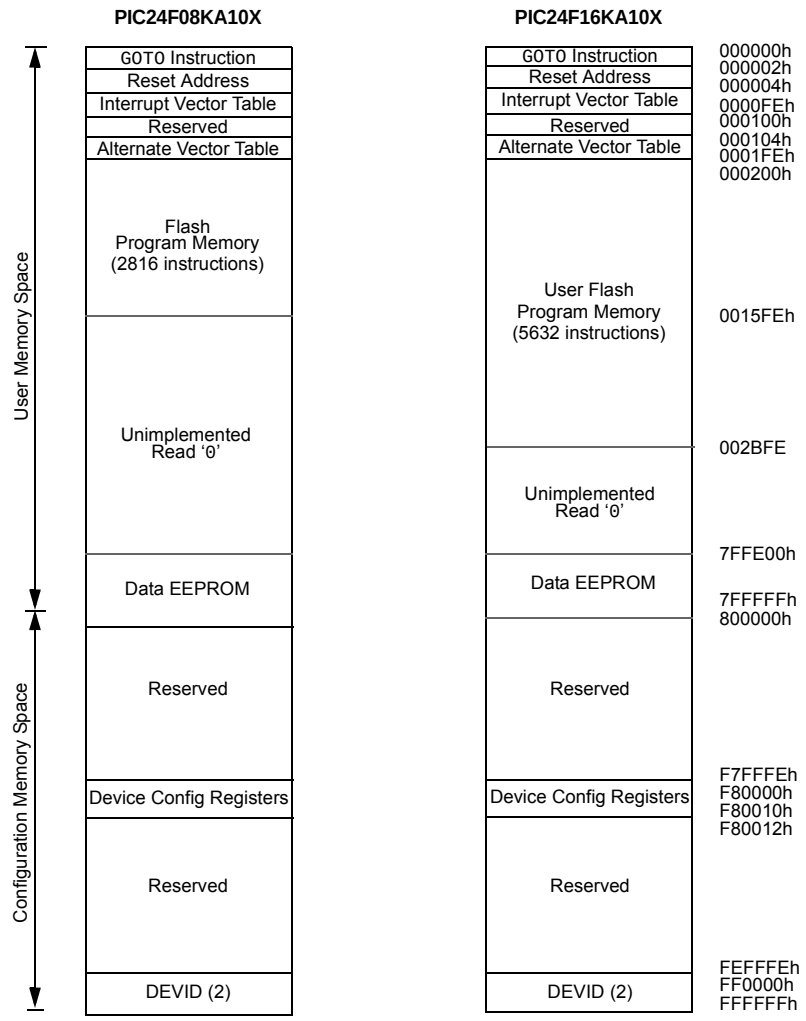
4.1 Program Address Space

The program address memory space of the PIC24F devices is 4M instructions. The space is addressable by a 24-bit value derived from either the 23-bit Program Counter (PC) during program execution, or from a table operation or data space remapping, as described in **Section 4.3 "Interfacing Program and Data Memory Spaces"**.

The user access to the program memory space is restricted to the lower half of the address range (000000h to 7FFFFFh). The exception is the use of TBLRD/TBLWT operations, which use TBLPAG<7> to permit access to the Configuration bits and Device ID sections of the configuration memory space.

Memory maps for the PIC24F16KA102 family of devices are displayed in Figure 4-1.

FIGURE 4-1: PROGRAM SPACE MEMORY MAP FOR PIC24F16KA102 FAMILY DEVICES



Note: Memory areas are not displayed to scale.

TABLE 4-17: REAL-TIME CLOCK AND CALENDAR REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ALRMVAL	0620	Alarm Value Register Window Based on ALRMPTR<15:0>																xxxx
ALCFGRPT	0622	ALRMEN	CHIME	AMASK3	AMASK2	AMASK1	AMASK0	ALRMPTR1	ALRMPTR0	ARPT7	ARPT6	ARPT5	ARPT4	ARPT3	ARPT2	ARPT1	ARPT0	0000
RTCVAL	0624	RTCC Value Register Window Based on RTCPTR<15:0>																xxxx
RCFGCAL	0626	RTCEN	—	RTCWREN	RTCSYNC	HALFSEC	RTCOE	RTCPTR1	RTCPTR0	CAL7	CAL6	CAL5	CAL4	CAL3	CAL2	CAL1	CAL0	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-18: DUAL COMPARATOR REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CMSTAT	0630	CMSIDL	—	—	—	—	—	C2EVT	C1EVT	—	—	—	—	—	—	C2OUT	C1OUT	0000
CVRCON	0632	—	—	—	—	—	—	—	—	CVREN	CVROE	CVRR	CVRSS	CVR3	CVR2	CVR1	CVR0	0000
CM1CON	0634	CON	COE	CPOL	CLPWR	—	—	CEVT	COUT	EVPOL1	EVPOL0	—	CREF	—	—	CCH1	CCH0	0000
CM2CON	0636	CON	COE	CPOL	CLPWR	—	—	CEVT	COUT	EVPOL1	EVPOL0	—	CREF	—	—	CCH1	CCH0	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-19: CRC REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CRCCON	0640	—	—	CSIDL	VWORD4	VWORD3	VWORD2	VWORD1	VWORD0	CRCFUL	CRCMPT	—	CRCGO	PLEN3	PLEN2	PLEN1	PLEN0	0040
CRCXOR	0642	X<15:1>															—	0000
CRCDAT	0644	CRC Data Input Register																0000
CRCWDAT	0646	CRC Result Register																0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-20: CLOCK CONTROL REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RCON	0740	TRAPR	IOPUWR	SBOREN	—	—	DPSLP	—	PMSLP	EXTR	SWR	SWDTEN	WDTO	SLEEP	IDLE	BOR	POR	(Note 1)
OSCCON	0742	—	COSC2	COSC1	COSC0	—	NOSC2	NOSC1	NOSC0	CLKLOCK	—	LOCK	—	CF	—	SOSCEN	OSWEN	(Note 2)
CLKDIV	0744	ROI	DOZE2	DOZE1	DOZE0	DOZEN	RCDIV2	RCDIV1	RCDIV0	—	—	—	—	—	—	—	—	3140
OSCTUN	0748	—	—	—	—	—	—	—	—	—	—	TUN5	TUN4	TUN3	TUN2	TUN1	TUN0	0000
REFOCON	074E	ROEN	—	ROSSLP	ROSEL	RODIV3	RODIV2	RODIV1	RODIV0	—	—	—	—	—	—	—	—	0000
HLVDCON	0756	HLVDEN	—	HLSIDL	—	—	—	—	—	VDIR	BGVST	IRVST	—	HLVDL3	HLVDL2	HLVDL1	HLVDL0	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: RCON register Reset values are dependent on the type of Reset.

2: OSCCON register Reset values are dependent on configuration fuses and by type of Reset.

TABLE 4-21: DEEP SLEEP REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets(1)
DSCON	0758	DSEN	—	—	—	—	—	—	—	—	—	—	—	—	—	DSBOR	RELEASE	0000
DSWAKE	075A	—	—	—	—	—	—	—	DSINT0	DSFLT	—	—	DSWDT	DSRTCC	DSMCLR	—	DSPOR	0000
DSGPR0	075C	Deep Sleep General Purpose Register 0																0000
DSGPR1	075E	Deep Sleep General Purpose Register 1																0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: The Deep Sleep registers are only reset on a VDD POR event.

TABLE 4-22: NVM REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
NVMCON	0760	WR	WREN	WRERR	PGMONLY	—	—	—	—	—	ERASE	NVMOP5	NVMOP4	NVMOP3	NVMOP2	NVMOP1	NVMOP0	0000(1)
NVMKEY	0766	—	—	—	—	—	—	—	—	NVMKEY7	NVMKEY6	NVMKEY5	NVMKEY4	NVMKEY3	NVMKEY2	NVMKEY1	NVMKEY0	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Reset value shown is for POR only. Value on other Reset states is dependent on the state of memory write or erase operations at the time of Reset.

TABLE 4-23: PMD REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0770	—	—	T3MD	T2MD	T1MD	—	—	—	I2C1MD	U2MD	U1MD	—	SPI1MD	—	—	ADC1MD	0000
PMD2	0772	—	—	—	—	—	—	—	IC1MD	—	—	—	—	—	—	—	OC1MD	0000
PMD3	0774	—	—	—	—	—	CMPMD	RTCCMD	—	CRCPMD	—	—	—	—	—	—	—	0000
PMD4	0776	—	—	—	—	—	—	—	—	—	—	—	EEMD	REFOMD	CTMUMD	HLVDMD	—	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

EXAMPLE 5-3: LOADING THE WRITE BUFFERS – ASSEMBLY LANGUAGE CODE

```
; Set up NVMCON for row programming operations
       MOV     #0x4004, W0                  ;
       MOV     W0, NVMCON                   ; Initialize NVMCON
; Set up a pointer to the first program memory location to be written
; program memory selected, and writes enabled
       MOV     #0x0000, W0                  ;
       MOV     W0, TBLPAG                   ; Initialize PM Page Boundary SFR
       MOV     #0x1500, W0                  ; An example program memory address
; Perform the TBLWT instructions to write the latches
; 0th_program_word
       MOV     #LOW_WORD_0, W2              ;
       MOV     #HIGH_BYTE_0, W3             ;
       TBLWTL  W2, [W0]                     ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                   ; Write PM high byte into program latch
; 1st_program_word
       MOV     #LOW_WORD_1, W2              ;
       MOV     #HIGH_BYTE_1, W3             ;
       TBLWTL  W2, [W0]                     ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                   ; Write PM high byte into program latch
;  2nd_program_word
       MOV     #LOW_WORD_2, W2              ;
       MOV     #HIGH_BYTE_2, W3             ;
       TBLWTL  W2, [W0]                     ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                   ; Write PM high byte into program latch
       •
       •
       •
; 32nd_program_word
       MOV     #LOW_WORD_31, W2             ;
       MOV     #HIGH_BYTE_31, W3            ;
       TBLWTL  W2, [W0]                     ; Write PM low word into program latch
       TBLWTH  W3, [W0]                     ; Write PM high byte into program latch
```

EXAMPLE 5-4: LOADING THE WRITE BUFFERS – ‘C’ LANGUAGE CODE

```
// C example using MPLAB C30

   #define NUM_INSTRUCTION_PER_ROW 64
int __attribute__ ((space(auto_psv))) progAddr = 0x1234     // Variable located in Pgm Memory
   unsigned int offset;
   unsigned int i;
   unsigned int progData[2*NUM_INSTRUCTION_PER_ROW];        // Buffer of data to write

   //Set up NVMCON for row programming
   NVMCON = 0x4004;                                         // Initialize NVMCON

   //Set up pointer to the first memory location to be written
   TBLPAG = __builtin_tblpage(&progAddr);                   // Initialize PM Page Boundary SFR
   offset = __builtin_tbloffset(&progAddr);                 // Initialize lower word of address

   //Perform TBLWT instructions to write necessary number of latches
   for(i=0; i < 2*NUM_INSTRUCTION_PER_ROW; i++)
   {
       __builtin_tblwtl(offset, progData[i++]);             // Write to address low word
       __builtin_tblwth(offset, progData[i]);               // Write to upper byte
       offset = offset + 2;                                 // Increment address
   }
```

REGISTER 9-4: REFOCON: REFERENCE OSCILLATOR CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ROEN	—	ROSSLP	ROSEL	RODIV3	RODIV2	RODIV1	RODIV0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ROEN:** Reference Oscillator Output Enable bit
1 = Reference oscillator is enabled on REFO pin
0 = Reference oscillator is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **ROSSLP:** Reference Oscillator Output Stop in Sleep bit
1 = Reference oscillator continues to run in Sleep
0 = Reference oscillator is disabled in Sleep

bit 12 **ROSEL:** Reference Oscillator Source Select bit
1 = Primary oscillator is used as the base clock(1)
0 = System clock is used as the base clock; base clock reflects any clock switching of the device

bit 11-8 **RODIV<3:0>:** Reference Oscillator Divisor Select bits
1111 = Base clock value divided by 32,768
1110 = Base clock value divided by 16,384
1101 = Base clock value divided by 8,192
1100 = Base clock value divided by 4,096
1011 = Base clock value divided by 2,048
1010 = Base clock value divided by 1,024
1001 = Base clock value divided by 512
1000 = Base clock value divided by 256
0111 = Base clock value divided by 128
0110 = Base clock value divided by 64
0101 = Base clock value divided by 32
0100 = Base clock value divided by 16
0011 = Base clock value divided by 8
0010 = Base clock value divided by 4
0001 = Base clock value divided by 2
0000 = Base clock value

bit 7-0 **Unimplemented:** Read as '0'

Note 1: The crystal oscillator must be enabled using the FOSC<2:0> bits; the crystal maintains the operation in Sleep mode.

FIGURE 13-2: TIMER2 (16-BIT SYNCHRONOUS) BLOCK DIAGRAM

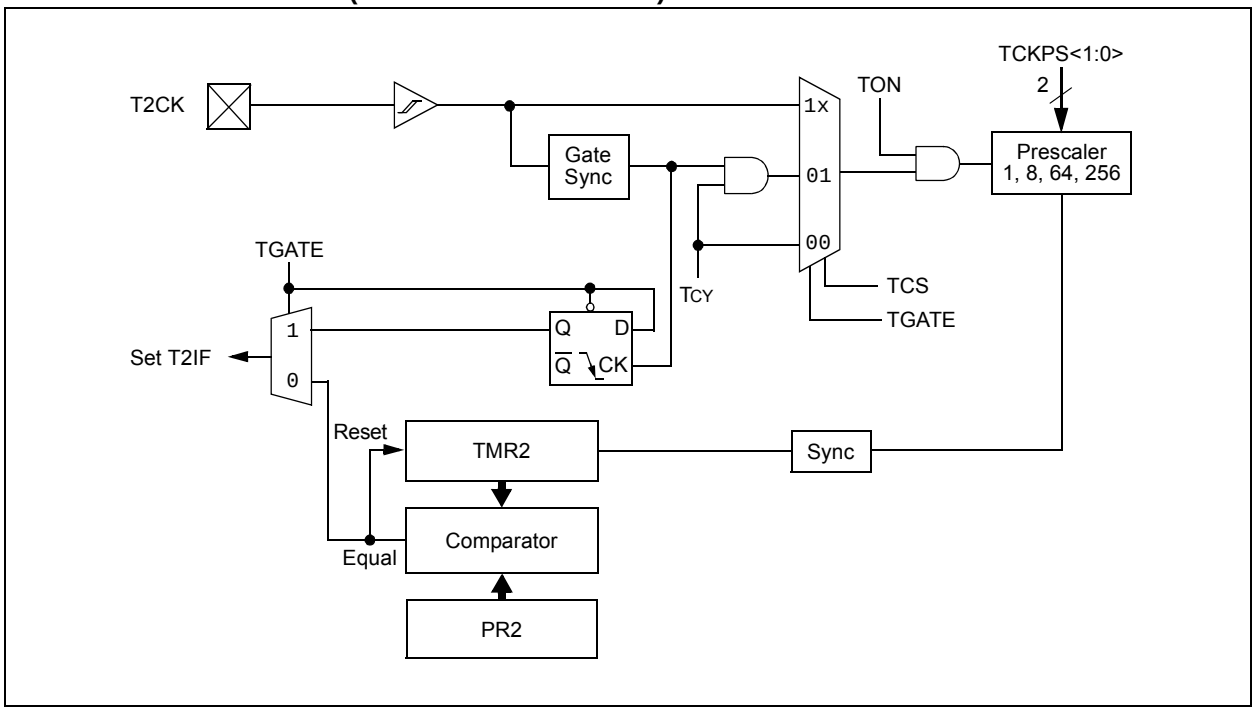
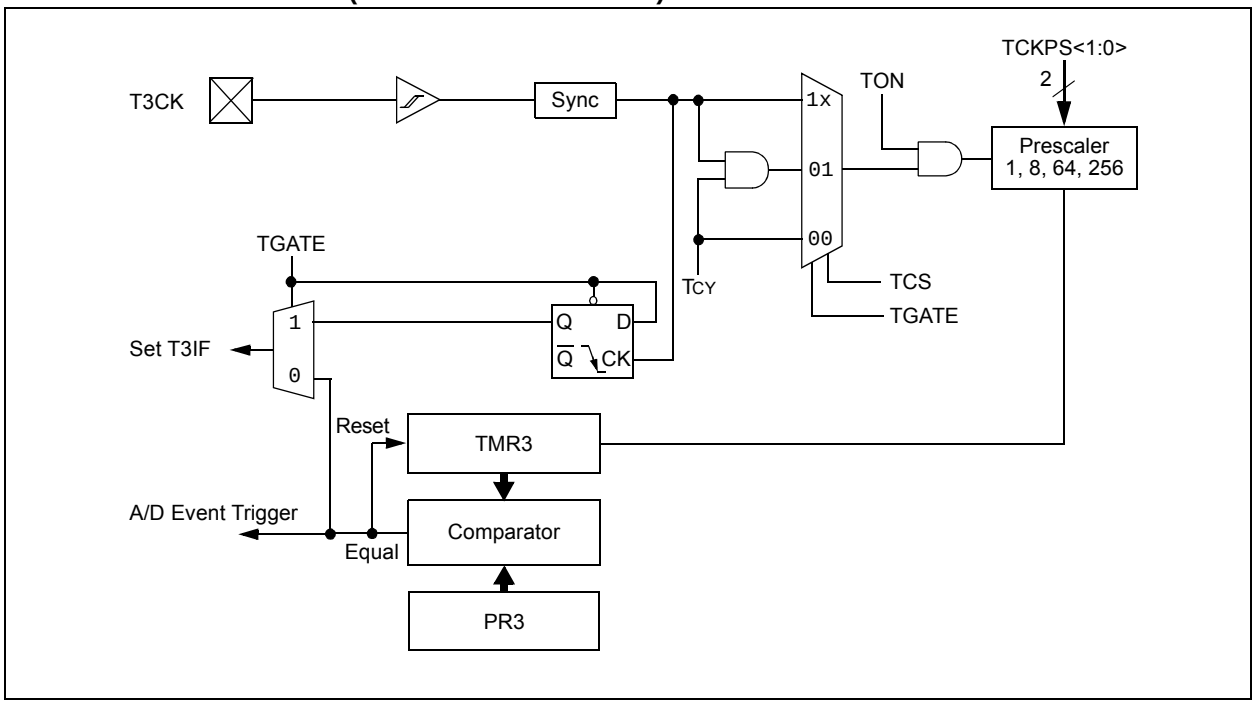


FIGURE 13-3: TIMER3 (16-BIT SYNCHRONOUS) BLOCK DIAGRAM



REGISTER 17-2: I2C1STAT: I2C1 STATUS REGISTER

R-0, HSC	R-0, HSC	U-0	U-0	U-0	R/C-0, HS	R-0, HSC	R-0, HSC
ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10
bit 15							bit 8

R/C-0, HS	R/C-0, HS	R-0, HSC	R/C-0, HSC	R/C-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC
IWCOL	I2COV	D/$\overline{A}$	P	S	R/$\overline{W}$	RBF	TBF
bit 7							bit 0

Legend:	C = Clearable bit	HS = Hardware Settable bit	HSC = Hardware Settable/Clearable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ACKSTAT:** Acknowledge Status bit
1 = NACK was detected last
0 = ACK was detected last
Hardware is set or clear at of Acknowledge.

bit 14 **TRSTAT:** Transmit Status bit
(When operating as I^2C™ master; applicable to master transmit operation.)
1 = Master transmit is in progress (8 bits + ACK)
0 = Master transmit is not in progress
Hardware is set at beginning of master transmission; hardware is clear at end of slave Acknowledge.

bit 13-11 **Unimplemented:** Read as '0'

bit 10 **BCL:** Master Bus Collision Detect bit
1 = A bus collision has been detected during a master operation
0 = No collision
Hardware is set at detection of bus collision.

bit 9 **GCSTAT:** General Call Status bit
1 = General call address was received
0 = General call address was not received
Hardware is set when address matches general call address; hardware is clear at Stop detection.

bit 8 **ADD10:** 10-Bit Address Status bit
1 = 10-bit address was matched
0 = 10-bit address was not matched
Hardware is set at match of 2nd byte of matched 10-bit address; hardware is clear at Stop detection.

bit 7 **IWCOL:** Write Collision Detect bit
1 = An attempt to write to the I2C1TRN register failed because the I^2C module is busy
0 = No collision
Hardware is set at occurrence of write to I2C1TRN while busy (cleared by software).

bit 6 **I2COV:** Receive Overflow Flag bit
1 = A byte was received while the I2C1RCV register is still holding the previous byte
0 = No overflow
Hardware is set at attempt to transfer to I2C1RCV (cleared by software).

bit 5 **D/$\overline{A}$:** Data/$\overline{Address}$ bit (when operating as I^2C slave)
1 = Indicates that the last byte received was data
0 = Indicates that the last byte received was the device address
Hardware is clear at device address match; hardware is set by a write to I2C1TRN or by reception of slave byte.

bit 4 **P:** Stop bit
1 = Indicates that a Stop bit has been detected last
0 = Stop bit was not detected last
Hardware is set or clear when Start, Repeated Start or Stop is detected.

REGISTER 19-10: ALMINSEC: ALARM MINUTES AND SECONDS VALUE REGISTER

U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	MINTEN2	MINTEN1	MINTEN0	MINONE3	MINONE2	MINONE1	MINONE0
bit 15							bit 8

U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	SECTEN2	SECTEN1	SECTEN0	SECONE3	SECONE2	SECONE1	SECONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **MINTEN<2:0>:** Binary Coded Decimal Value of Minute’s Tens Digit bits
Contains a value from 0 to 5.

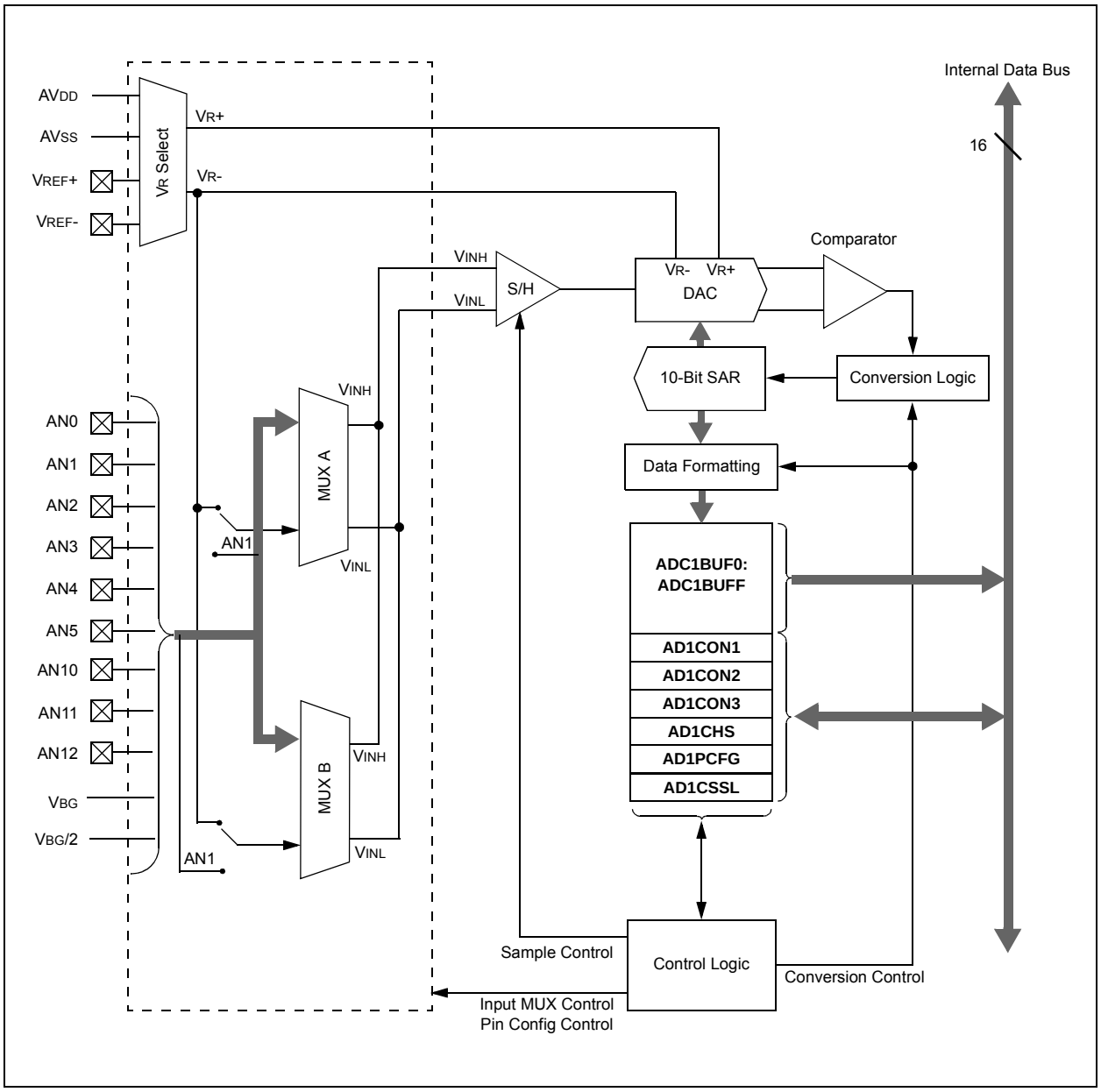
bit 11-8 **MINONE<3:0>:** Binary Coded Decimal Value of Minute’s Ones Digit bits
Contains a value from 0 to 9.

bit 7 **Unimplemented:** Read as ‘0’

bit 6-4 **SECTEN<2:0>:** Binary Coded Decimal Value of Second’s Tens Digit bits
Contains a value from 0 to 5.

bit 3-0 **SECONE<3:0>:** Binary Coded Decimal Value of Second’s Ones Digit bits
Contains a value from 0 to 9.

FIGURE 22-1: 10-BIT HIGH-SPEED A/D CONVERTER BLOCK DIAGRAM



REGISTER 26-6: FPOR: RESET CONFIGURATION REGISTER

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	U-0	R/P-1	R/P-1
MCLRE(2)	BORV1(3)	BORV0(3)	I2C1SEL(1)	PWRTEN	—	BOREN1	BOREN0
bit 7							bit 0

Legend:			
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **MCLRE:** $\overline{\text{MCLR}}$ Pin Enable bit(2)
1 = $\overline{\text{MCLR}}$ pin is enabled; RA5 input pin is disabled
0 = RA5 input pin is enabled; $\overline{\text{MCLR}}$ is disabled

bit 6-5 **BORV<1:0>:** Brown-out Reset Enable bits(3)
11 = Brown-out Reset is set to the lowest voltage
10 = Brown-out Reset
01 = Brown-out Reset is set to the highest voltage
00 = Low-Power Brown-out Reset occurs around 2.0V

bit 4 **I2C1SEL:** Alternate I2C1 Pin Mapping bit(1)
0 = Alternate location for SCL1/SDA1 pins
1 = Default location for SCL1/SDA1 pins

bit 3 **PWRTEN:** Power-up Timer Enable bit
0 = PWRT is disabled
1 = PWRT is enabled

bit 2 **Unimplemented:** Read as '0'

bit 1-0 **BOREN<1:0>:** Brown-out Reset Enable bits
11 = Brown-out Reset is enabled in hardware; SBOREN bit is disabled
10 = Brown-out Reset is enabled only while device is active and disabled in Sleep; SBOREN bit is disabled
01 = Brown-out Reset is controlled with the SBOREN bit setting
00 = Brown-out Reset is disabled in hardware; SBOREN bit is disabled

Note 1: Applies only to 28-pin devices.
2: The MCLRE fuse can only be changed when using the VPP-Based ICSP™ mode entry. This prevents a user from accidentally locking out the device from the low-voltage test entry.
3: Refer to Section 29.0, Electrical Characteristics for the BOR voltages.

TABLE 29-9: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage(4)**	—	—	—	—	
DI10		I/O Pins	VSS	—	0.2 VDD	V	
DI15		$\overline{\text{MCLR}}$	VSS	—	0.2 VDD	V	
DI16		OSCI (XT mode)	VSS	—	0.2 VDD	V	
DI17		OSCI (HS mode)	VSS	—	0.2 VDD	V	
DI18		I/O Pins with I2C™ Buffer	VSS	—	0.3 VDD	V	SMBus disabled
DI19		I/O Pins with SMBus Buffer	VSS	—	0.8	V	SMBus enabled
	VIH(5)	**Input High Voltage(4)**	—	—	—	—	
DI20		I/O Pins:					
		with Analog Functions	0.8 VDD	—	VDD	V	
		Digital Only	0.8 VDD	—	VDD	V	
DI25		$\overline{\text{MCLR}}$	0.8 VDD	—	VDD	V	
DI26		OSCI (XT mode)	0.7 VDD	—	VDD	V	
DI27		OSCI (HS mode)	0.7 VDD	—	VDD	V	
DI28		I/O Pins with I2C Buffer:					
		with Analog Functions	0.7 VDD	—	VDD	V	
		Digital Only	0.7 VDD	—	VDD	V	
DI29		I/O Pins with SMBus	2.1	—	VDD	V	2.5V ≤ VPIN ≤ VDD
DI30	ICNPU	**CNx Pull-up Current**	50	250	500	μA	VDD = 3.3V, VPIN = VSS
	IIL	**Input Leakage Current(2,3)**					
DI50		I/O Ports	—	0.050	±0.100	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		VREF+, VREF-, AN0, AN1	—	0.300	±0.500	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI55		$\overline{\text{MCLR}}$	—	—	±5.0	μA	VSS ≤ VPIN ≤ VDD
DI56		OSCI	—	—	±5.0	μA	VSS ≤ VPIN ≤ VDD, XT and HS modes

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: Refer to Table 1-2 for I/O pin buffer types.

5: VIH requirements are met when internal pull-ups are enabled.

TABLE 29-13: COMPARATOR DC SPECIFICATIONS

Operating Conditions: 2.0V < VDD < 3.6V Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended							
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Comments**
D300	VIOFF	Input Offset Voltage*	—	20	40	mV	
D301	VICM	Input Common Mode Voltage*	0	—	VDD	V	
D302	CMRR	Common Mode Rejection Ratio*	55	—	—	dB	

* Parameters are characterized but not tested.

TABLE 29-14: COMPARATOR VOLTAGE REFERENCE DC SPECIFICATIONS

Operating Conditions: 2.0V < VDD < 3.6V Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended							
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Comments**
VRD310	CVRES	Resolution	VDD/24	—	VDD/32	LSb	
VRD311	CVRAA	Absolute Accuracy	—	—	AVDD – 1.5	LSb	
VRD312	CVRUR	Unit Resistor Value (R)	—	2k	—	Ω	

TABLE 29-15: INTERNAL VOLTAGE REFERENCES

Operating Conditions: 2.0V < VDD < 3.6V Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended							
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Comments**
	VBG	Internal Band Gap Reference	1.14	1.2	1.26	V	
	TIRVST	Internal Reference Stabilization Time	—	200	250	μs	

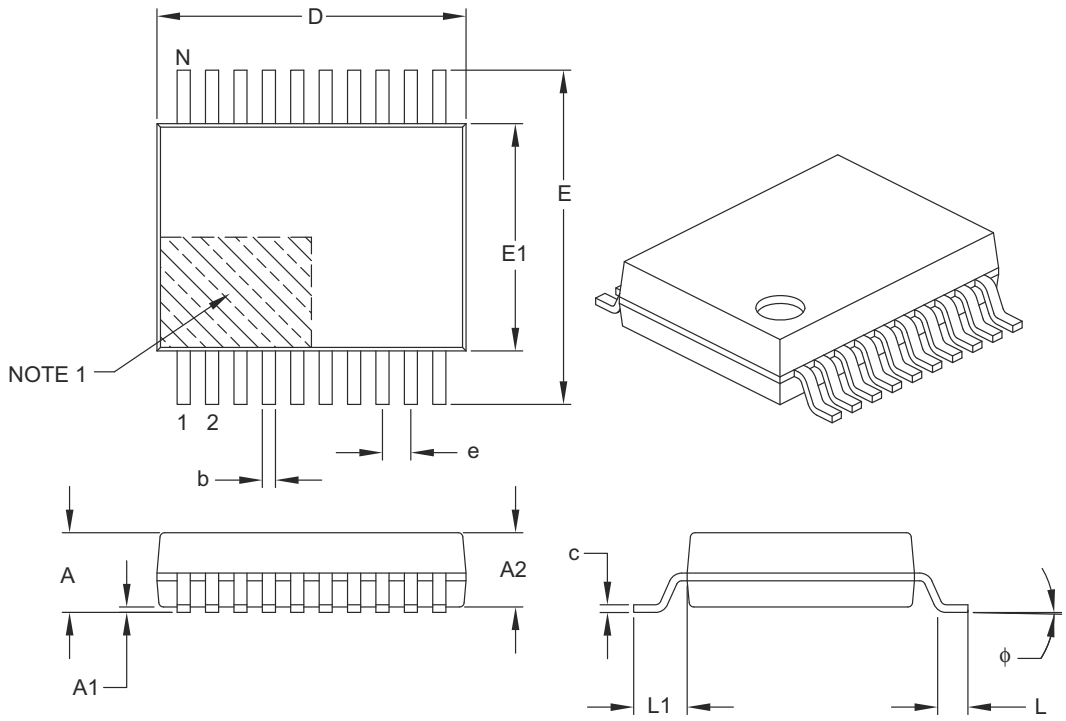
TABLE 29-16: CTMU CURRENT SOURCE SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
	IOUT1	CTMU Current Source, Base Range	—	550	—	nA	CTMUICON<1:0> = 01
	IOUT2	CTMU Current Source, 10x Range	—	5.5	—	μA	CTMUICON<1:0> = 10
	IOUT3	CTMU Current Source, 100x Range	—	55	—	μA	CTMUICON<1:0> = 11

Note 1: Nominal value at the center point of the current trim range (CTMUICON<7:2> = 000000).

20-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	6.90	7.20	7.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-072B

20-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

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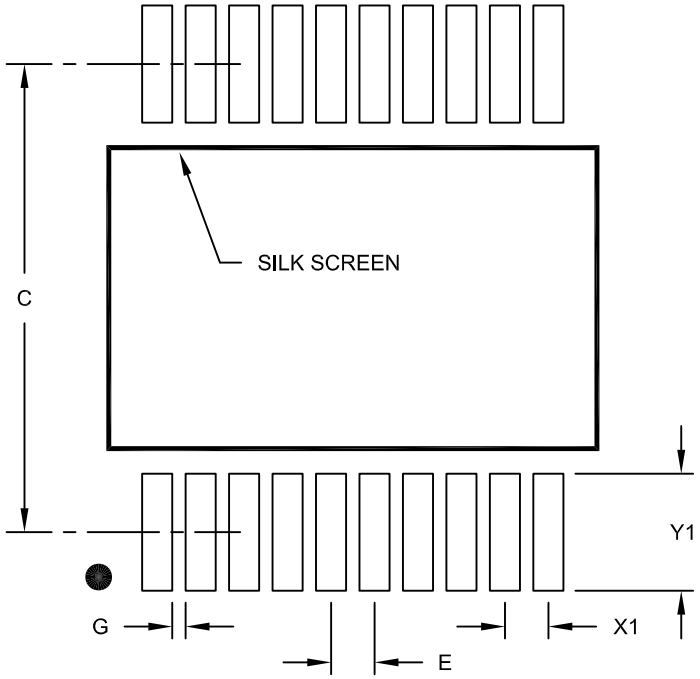

RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		7.20	
Contact Pad Width (X20)	X1			0.45
Contact Pad Length (X20)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

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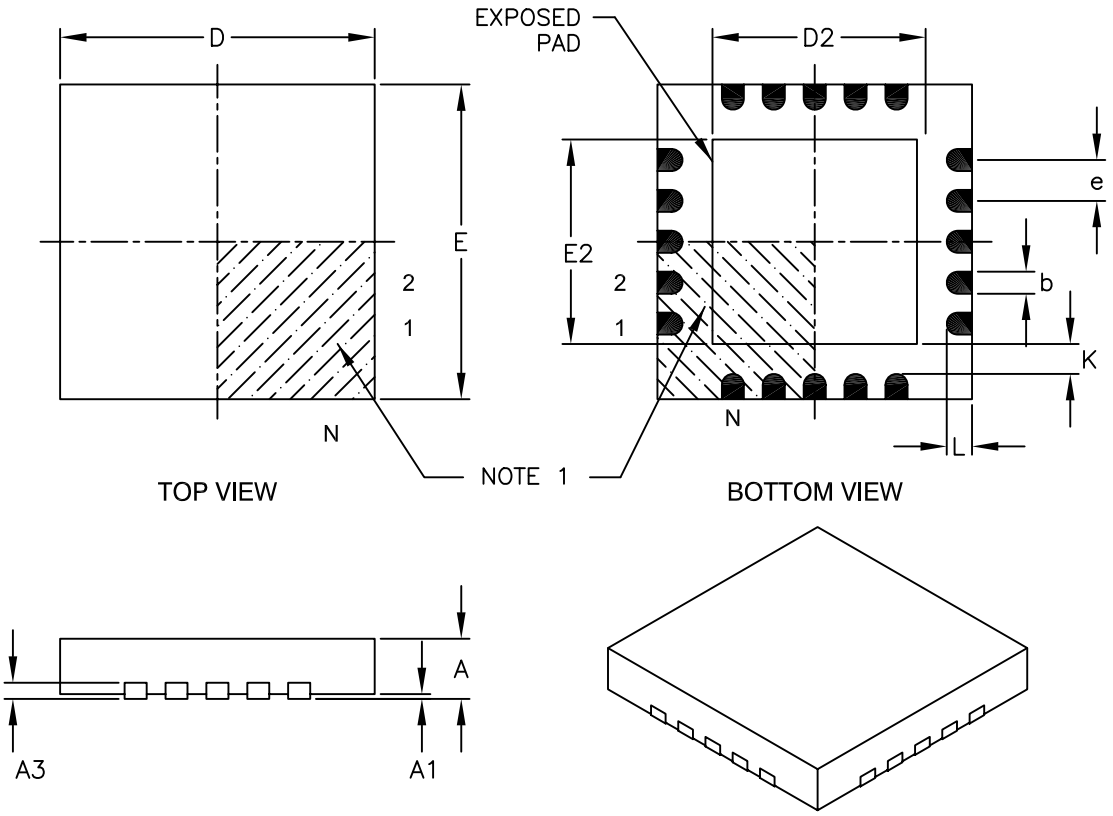
20-Lead Plastic Quad Flat, No Lead Package (MQ) – 5x5x0.9 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		5.00 BSC	
Exposed Pad Width	E2	3.15	3.25	3.35
Overall Length	D		5.00 BSC	
Exposed Pad Length	D2	3.15	3.25	3.35
Contact Width	b	0.25	0.30	0.35
Contact Length	L	0.35	0.40	0.45
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-139B

APPENDIX A: REVISION HISTORY

Revision A (November 2008)

Original data sheet for the PIC24F16KA102 family of devices.

Revision B (March 2009)

Section 29.0 "Electrical Characteristics" was revised and minor text edits were made throughout the document.

Revision C (October 2011)

- Changed all instances of DSWSRC to DSWAKE.
- Corrected Example 5-2.
- Corrected Example 5-4.
- Corrected Example 6-1.
- Corrected Example 6-3.
- Added a comment to Example 6-5.
- Corrected Figure 9-1 to connect the SOSCI and SOSCO pins to the Schmitt trigger correctly.
- Added register descriptions for PMD1, PMD2, PMD3 and PMD4.
- Added note that RTCC will run in Reset.
- Corrected time values of ADCS (AD1CON3<5:0>).
- Corrected CH0SB and CH0SA (AD1CHS<11:8> and AD1CHS<3:0>) to correctly reference AVDD and AN3.
- Added description of PGCF15 and PGCF14 (AD1PCFG<15:14>).
- Edited Figure 22-2 to correctly reference RIC and the A/D capacitance.
- Changed all references from CTEDG1 to CTED1.
- Changed all references from CTEDG2 to CTED2.
- Changed description of CMIDL: it used to say it disables all comparators in Idle, now only disables interrupts in Idle mode.
- Changed all references of RTCCKSEL to RTCOSC.
- Changed all references of DSLPBOR to DSBOREN.
- Changed all references of DSWCKSEL to DSWDTOSC
- Imported Figure 40-9 from PIC24F FRM, Section 40.
- Added spec for BOR hysteresis.
- Edited Note 1 for Table 29-5 to further describe LPBOR.
- Edited max values of DC20d and DC20e on Table 29-6.
- Edited typical value for DC61-DC61c in Table 29-8.
- Edited Note 2 of Table 29-8.
- Added Note 5 to Table 29-9.
- Added Table 29-15.
- Added AD08 and AD09 in Table 29-26.
- Added Note 3 to Table 29-26.
- Imported Figure 40.10 from PIC24F FRM, Section 40.
- Deleted TVREG spec.
- Imported Figure 15-5 from PIC24F FRM, Section 15.
- Imported Table 15-4 from PIC24F FRM, Section 15.
- Imported Figure 16-22 from PIC24F FRM, Section 16.
- Imported Table 16-9 from PIC24F FRM, Section 16.
- Imported Figure 16-23 from PIC24F FRM, Section 16.
- Imported Table 16-10 from PIC24F FRM, Section 16.
- Imported Figure 21-24 from PIC24F FRM. Section 21.
- Imported Figure 21-25 from PIC24F FRM, Section 21.
- Imported Table 21-5 from PIC24F FRM, Section 21.
- Imported Figure 23-17 from PIC24F FRM, Section 23.
- Imported Table 23-3 from PIC24F FRM, Section 23.
- Imported Figure 23-18 from PIC24F FRM, Section 23.
- Imported Table 23-4 from PIC24F FRM, Section 23.
- Imported Figure 23-19 from PIC24F FRM, Section 23.
- Imported Table 23-5 from PIC24F FRM, Section 23.
- Imported Figure 23-20 from PIC24F FRM, Section 23.
- Imported Table 23-6 from PIC24F FRM, Section 23.
- Imported Figure 24-33 from PIC24F FRM, Section 24.
- Imported Table 24-6 from PIC24F FRM, Section 24.
- Imported Figure 24-34 from PIC24F FRM, Section 24.
- Imported Table 24-7 from PIC24F FRM, Section 24.
- Imported Figure 24-35 from PIC24F FRM, Section 24.
- Imported Table 24-8 from PIC24F FRM, Section 24.
- Imported Figure 24-36 from PIC24F FRM, Section 24.
- Imported Table 24-9 from PIC24F FRM, Section 24.

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